2nd Call for Papers

25th EUROPEAN SYMPOSIUM ON RELIABILITY OF ELECTRON DEVICES, FAILURE PHYSICS AND ANALYSIS
ESREF 2014 Berlin, Germany
September 29 – October 2, 2014
Technische Universität Berlin
www.esref2014.org

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SCOPE OF PAPERS

Papers are requested on the following topics:

• Quality and Reliability Assessment Techniques and Methods for Devices and Systems
• Physical Modeling and Simulation for Reliability Prediction
• Advanced Failure Analysis: Defect Detection and Analysis
• Failure Mechanisms of Advanced Processes and Materials
• Failure analysis and Reliability of Advanced and Nanoscale Electronics
• Focused Ion Beam Processes (EFUG)
• Power Devices Reliability
• Packaging and Assembly Reliability
• Organic electronics: OLED, Electronic Ink, TFT
• 3D Metallization
• Nano-electronics, Nano-electronic Materials for Solid State Devices, Solar Cells and Display
• Photonics, Optoelectronics
• Bio-engineering, Bio-electronics, Bio-sensors, Nano-Bio-technologies

REGISTRATION FEES

<table>
<thead>
<tr>
<th>Category</th>
<th>Before 29.08.2014</th>
<th>After 29.08.2014</th>
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<tr>
<td>Non member</td>
<td>650 €</td>
<td>750 €</td>
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<tr>
<td>VDE member*</td>
<td>600 €</td>
<td>700 €</td>
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<tr>
<td>Students*</td>
<td>450 €</td>
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Participants applying for the membership fee must include a copy of their membership card to the registration form. A photocopy of the student card must be included.

EQUIPMENT EXHIBITION

The exhibition of ESREF 2014 offers you an excellent opportunity to show your company’s visibility in the important topic of service providers, equipment, manufacturers and suppliers. The event provides an excellent platform to present your international projects and for the exchange with customers and interested parties from all over the world.

For your exhibition options at ESREF 2014, please contact VDE Conference Services: jasmin.kayadelen@vde.com

ORGANIZATION

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SUBMISSION GUIDELINES

The deadline for the submission of abstracts is March 14th, 2014.

The 2-page abstract should include a five-line text summary, all images, figures and references, as well as the complete postal and e-mail address of the corresponding author. Please note that abstracts and papers must be in English. Please indicate your preference for oral or poster presentation.

Authors are requested to upload a file in Adobe Acrobat PDF. Further information is available at: www.esref2014.org

IMPORTANT DATES

March 14th, 2014 Submission of abstracts
May 5th, 2014 Notification of acceptance
June 20th, 2014 Submission of manuscripts

Elsevier Science will publish the ESREF 2014 proceedings as a special issue of the scientific journal "Microelectronics Reliability".
ESREF 2014, the 25th anniversary of the European Symposium on Reliability of Electron Devices will take place in Berlin (Germany) as a 3-day event from September 30th to October 2nd, 2014.

This international symposium continues to focus on recent developments and future directions in quality and reliability management of materials, devices and circuits for micro, nano, and optoelectronics. It provides a European forum for developing all aspects of reliability management and innovative analysis techniques for present and future electronic applications.

A word from the general chair

To characterize the dynamic potential of Berlin, I personally like to use the term “city of the unexpected”. Take on the surprise which Berlin offers its people, be it visitors or locals. And we, the organizers of ESREF 2014, take our part by making the conference itself an unexpected one – unexpectedly productive with 6 topical tracks, a special merge of tutorials, sessions and workshops. While focusing on rapidly growing topics like organic devices, 3D packaging and wide bandgap (power) devices, the conference is solidly grounded on industry oriented fundamentals of microelectronics, power devices and respective failure analysis. For the first time, the European FIB User Group, EFUG, is integrated as one large topical track in the conference program.

Let the different spices served at ESREF2014 inspire you, and expand your Berlin experience with our social event arranged in the Berlin club scene area “Kulturbrauerei”.

We are eager to welcome you!

Christian Boit

KEYNOTE SPEECHES
Organic PV Stability: Designed To Last
Ronn Andriessen (Solliance/Holst Centre, NLD)

OLEDs: Quality and Reliability
Volker van Elsbergen (Philips Research, Aachen, GER)

TUTORIALS
Organic Semiconductors: Novel Materials for Optoelectronic Application
Selina Otthof (University Köln GER); Jens Meyer (Philips Research, Aachen, GER)

Drift and reliability mechanisms in GaN based power devices for high voltage switching applications: The current understanding
Hans-Joachim Würfl (FBH, Berlin, GER)

Managing the effects of mechanical stress in 3D-integrated systems
Ehrenfried Zschech (FhG IZFP, Dresden, GER)

Asking the right questions (be)for(e) Failure Analysis
Peter Jacob (EMPA, Zürich, CHE)

INVITED TALKS
Lifetime Modeling and Simulation of Power Modules for Hybrid Electrical / Electrical Vehicles
Markus Thoen (Infineon, GER)

Performance – Reliability Trade-Offs for High-K RRAM
Nagarajan Raghavan (Singapore Univ. of Techn. and Design, SIN)

Enabling Higher Fault Isolation Resolution through Advanced Optics
Keith Serrels (DCG Systems, Fremont CA, USA)

Flip Chip Package Reliability
René Rongen (NXP Semiconductors, Nijmegen, NLD)

3D Reliability
Paul Ho (University of Texas at Austin, USA)

MEMS Reliability – Current Status and Challenges
Mervi Paulasto-Kröckel (University Aalto, FIN)

Precise Nanofabrication with Multiple Ion Beams for Advanced Circuit Edit
Huineng Wu (Carl Zeiss LLC, Peabody MA, USA)

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M. VANZI University of Cagliari (IT)

Topic I: Organic Devices
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